

Sotomayor, John

From: PLUS [PLUS2@uspto.gov]
Sent: Friday, May 11, 2007 1:01 PM
To: Sotomayor, John
Subject: PLUS Results for serial number: 10555651



10555651_WDS.
txt



10555651_LIST.
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10555651_WES
T.txt



10555651_CLST
ITLES.txt



10555651_QUAL
.txt



10555651_EAST
.txt



10555651_CLS.t
xt



10555651_result
s.east

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SEARCH NOTES FOR EAST, IEEE, INSPEC, IP.COM, AND PROQUEST

SERIAL NUMBER

10555651

EAST SEARCH

EAST: search history attached

Search terms:

semiconductor same (package or device or assembly) same multilayer same dielectric same substrate

bias same control

ground same conductor

ground same via

resistance same film same surface

electromagnetic same (shield or shielded or shielding)

(semiconductor and (package or device or assembly) and multilayer and dielectric and substrate and bias and control and ground and conductor and ground and via and resistance and film and surface and electromagnetic and (shield or shielded or shielding)).clm.

IEEE SEARCH

Sun, 16 Sep 2007, 6:35:44 PM EST

Recent Search Queries

Results

#1 ((semiconductor and (package or device or assembly) and multilayer and dielectric and substrate and bias and control and ground and conductor and ground and via and resistance and film and surface and electromagnetic and (shield or shielded or shielding))<in>metadata)

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INSPEC SEARCH

Search history:

No.	Database	Search term	Info added since	Results	
CP		[Clipboard]		0	-
1	INZZ	semiconductor AND (package OR device OR assembly) AND multilayer AND dielectric AND substrate AND bias AND control AND ground AND conductor AND ground AND via AND resistance AND film AND surface AND electromagnetic AND (shield OR shielded OR shielding)	unrestricted	0	

File View Edit Tools Window Help

Search, List, Browse, Group, Clear

DB: US-PGPUB

Default operator: OR

Highlight all hit items initially

(semiconductor and (package or device or assembly) and multilayer and dielectric and substrate and bias and control and ground and conductor and ground and via and resistance and film and surface and electromagnetic and (shield or shielded or shielding)).clm

- Drafts
- Pending
- Active
 - L1: (1076) semiconductor same (package or device or assembly) same multilayer same dielectric sam...
 - L2: (202795) bias same control
 - L3: (118146) ground same conductor
 - L4: (154904) ground same via
 - L5: (144755) resistance same film same surface
 - L6: (56505) electromagnetic same (shield or shielded or shielding)
 - L8: (4) 3 and 7
 - L7: (38) 1 and 2
 - L9: (23) Combined citation search 1
 - L10: (50) (US-4403208-\$ or US-4947171-\$ or US-5877802-\$ or US-5942957-\$ or US-6160773-\$ or US-554...
 - L11: (3) MATSUO-KOICHI-\$ in.
 - L12: (0) TAMAKI-TSUTOMU-\$ in.
 - L13: (1) SUZUKI-TAKUYA-\$ in.
 - L14: (1) (semiconductor and (package or device or assembly) and multilayer and dielectric and sub...
 - L15: (7241) ((342/175) or (342/70) or (343/700MS)) CCLS.
 - L17: (4) 1 and 16
 - L16: (6004) 15 and @ad<="20050324"
- Failed
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 - 10555651_results
 - OACS UDC
 - OACS UDC (1)
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Document	Pages	Title	Inventor	Current	OC
1. US 2007004, 2007022	42	High frequency package, tr Matsuo, Koi 342/175		25	

Search Terms	Total	USPAT	US-PGP	EPO	JPO	Derive
1 ASSEMBLIES	103901					
2 ASSEMBLY	373759					
3 ASSEMBLYS	49					
4 BLA	1847					
5 BIAS	111655					
6 BIUM	7					
7 BIUMS	0					
8 CONDUCTOR	87584					
9 CONDUCTOR	57609					

PGPUB-DOCUMENT- 20070040735

NUMBER:

PGPUB-FILING-TYPE:

DOCUMENT-IDENTIFIER: US 20070040735 A1

TITLE: High frequency package, transmitting and receiving module and wireless equipment

PUBLICATION- February 22, 2007

Ready

IP.COM SEARCH

semiconductor and (package or device or assembly) and multilayer and dielectric and substrate and bias and control and ground and conductor and ground and via and resistance and film and surface and electromagnetic and (shield or shielded or shielding)

No records matched your search.

PROQUEST SEARCH

(semiconductor and (package or device or assembly) and multilayer and dielectric and substrate and bias and control and ground and conductor and ground and via and resistance and film and surface and electromagnetic and (shield or shielded or shielding)).clm.

No relevant documents found.